

NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.

2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.

3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)

4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)

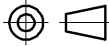

REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.


5 THIS IS PACKAGED IN TRAY. (60pcs/TRAY)



6. BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.

7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

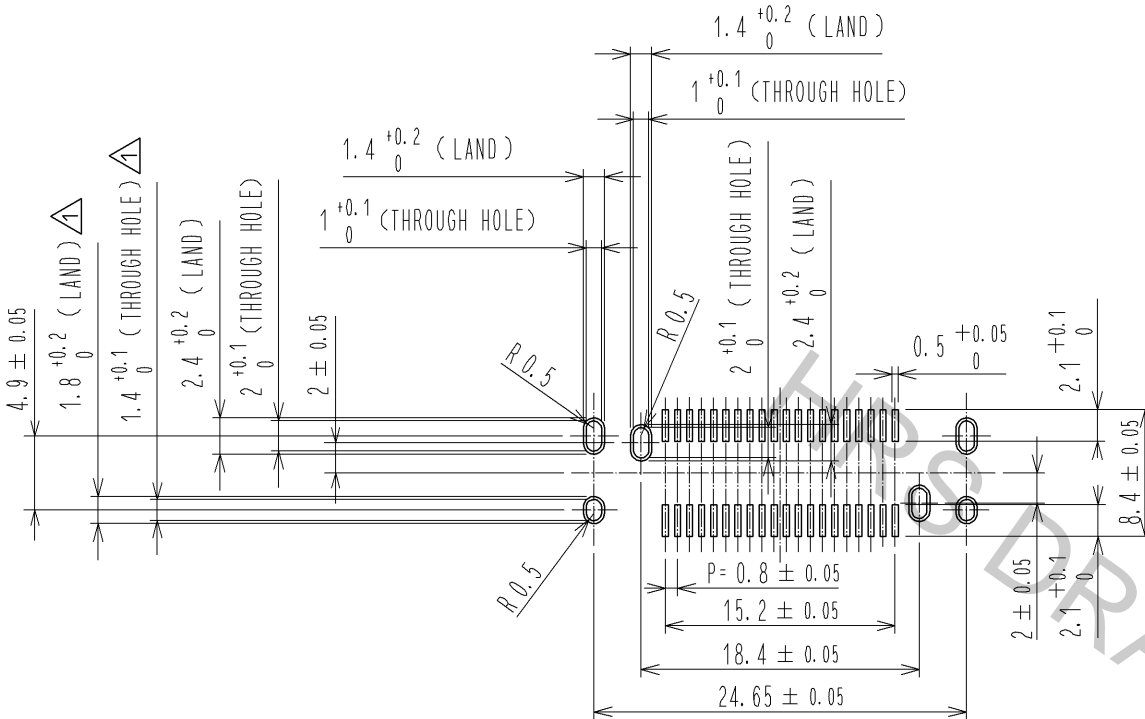
| | | | | | |
|-----|-----------------|-----------------------------|-----|--------------|-----------------------------|
| 3 | PHOSPHOR BRONZE | CONTACT AREA:GOLD 0.1 μm | 5 | COPPER ALLOY | LEAD AREA:TIN-PLATING 1 μm |
| | | LEAD AREA:GOLD 0.03 μm | | | UNDER PLATING:NICKEL 1.3 μm |
| | | UNDER PLATING:NICKEL 1.3 μm | | | |
| 2 | POLYAMIDE | BLACK UL94V-0 | 4 | COPPER ALLOY | CONTACT AREA:GOLD 0.1 μm |
| 1 | POLYAMIDE | BLACK UL94V-0 | | | LEAD AREA:TIN-PLATING 1 μm |
| | | | | | UNDER PLATING:NICKEL 1.3 μm |
| NO. | MATERIAL | FINISH , REMARKS | NO. | MATERIAL | FINISH , REMARKS |

| | | | | | | | |
|-------------|---|-------|---|--------------------------|----------|--------------|------------|
| UNITS mm |  | SCALE | COUNT | DESCRIPTION OF REVISIONS | DESIGNED | CHECKED | DATE |
| | | 2 : 1 |  3 | DIS-F-005578 | TH. SANO | KI. HIROKAWA | 11. 07. 21 |

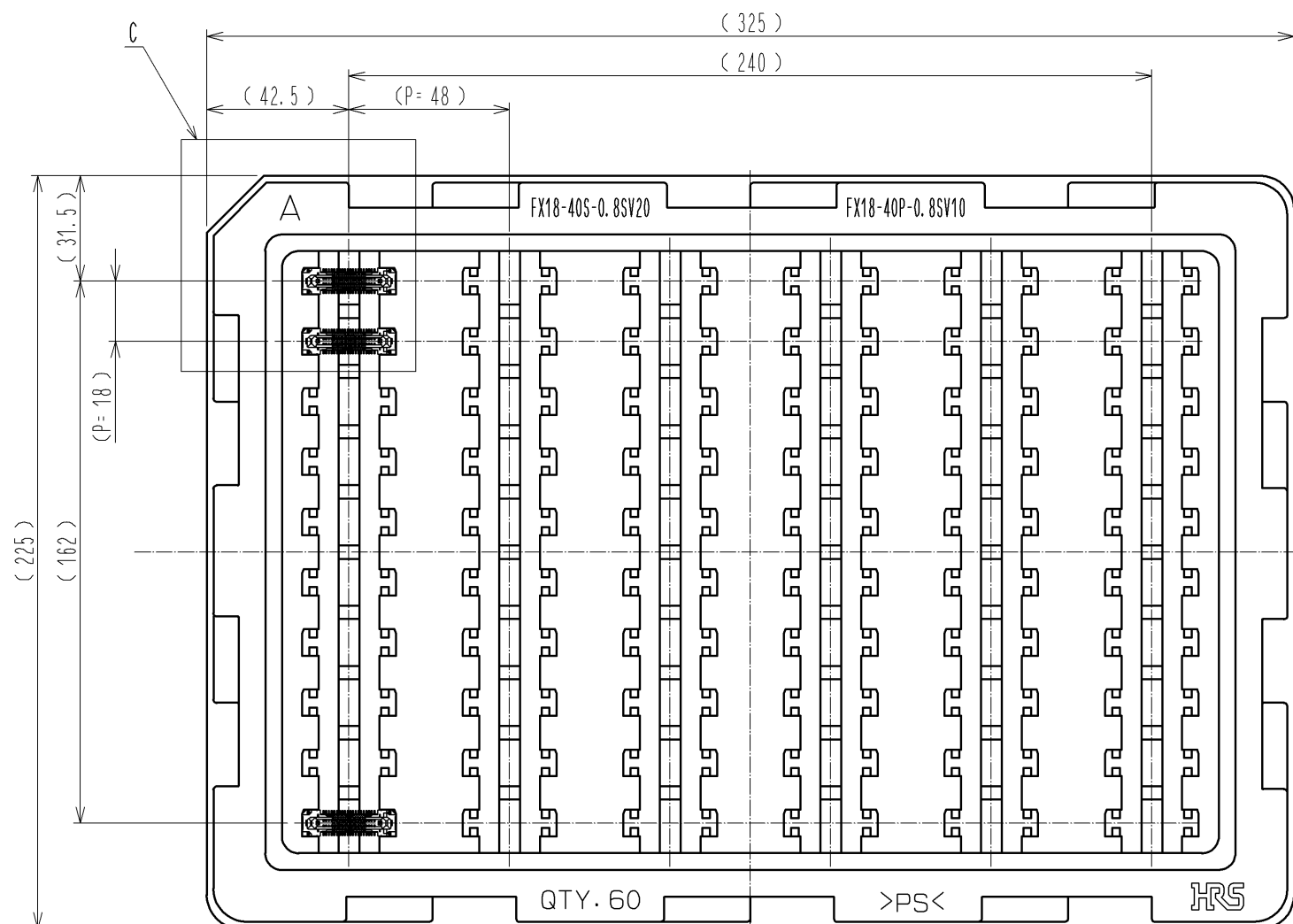
| | | | | |
|---|------------------------|------------|-------------|-------------------|
|  HIROSE ELECTRIC CO., LTD. | APPROVED : HS. OKAWA | 11. 03. 18 | DRAWING NO. | EDC3-334382-00 |
| | CHECKED : KI. HIROKAWA | 11. 03. 18 | PART NO. | FX18-40P-0. 8SV10 |
| | DESIGNED : TH. SANO | 11. 03. 18 | CODE NO. | CL579-0022-2-00 |
| | DRAWN : TH. SANO | 11. 03. 18 | | |
| | | | | |



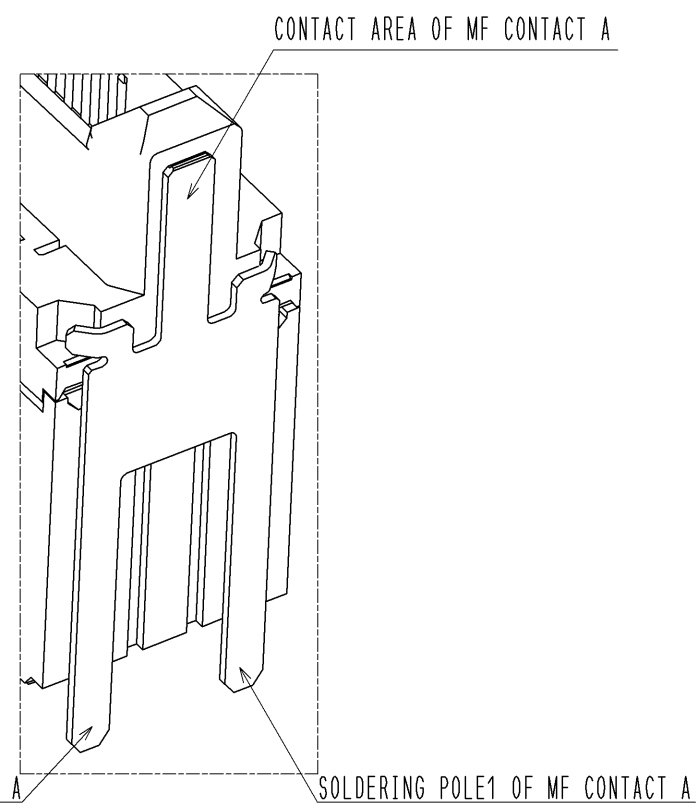
RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
(PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)



5 DRAWING FOR PACKING(1:2)

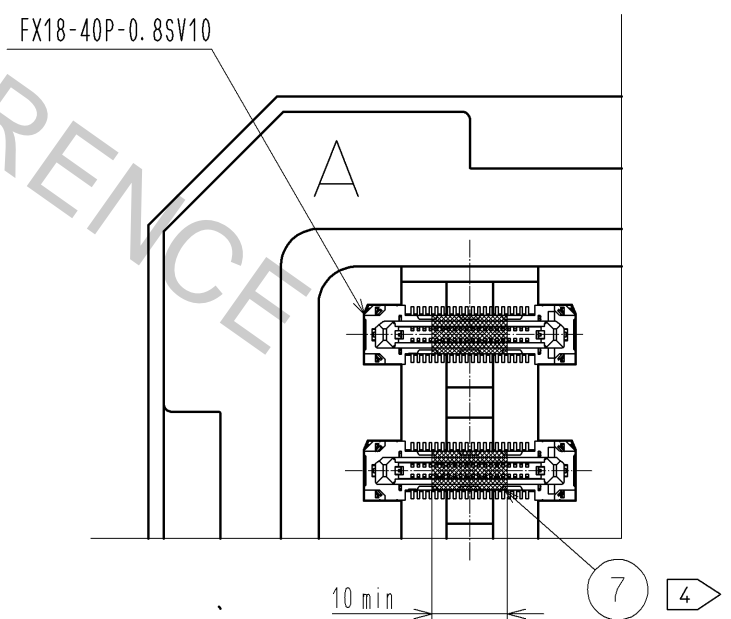


8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.

C(1:1)



| | | |
|-----|-------------|------------------|
| HRS | DRAWING NO. | EDC3-334382-00 |
| | PART NO. | FX18-40P-0.8SV10 |
| | CODE NO. | CL579-0022-2-00 |
| | | |